PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT6507862

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
S M AKRAMUS SALEHIN	01/08/2021
LAE-HOON KIM	01/20/2021
HANNES PESSENTHEINER	12/22/2020
SHUHUA ZHANG	01/08/2021
SANGHYUN CHI	12/31/2020
ERIK VISSER	12/31/2020
SHANKAR THAGADUR SHIVAPPA	01/06/2021

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17128544

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 512-200-9737
Email: npasarya@mooreiplaw.com
Correspondent Name: MOORE IP/QUALCOMM
Address Line 1: 13359 N HWY 183, #406-243
Address Line 4: AUSTIN, TEXAS 78750

ATTORNEY DOCKET NUMBER:	2101125
NAME OF SUBMITTER:	NISHI PASARYA
SIGNATURE:	/Nishi Pasarya/
DATE SIGNED:	01/21/2021

Total Attachments: 21

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ASSIGNMENT

WHEREAS, WE,

1. **S M Akramus SALEHIN,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

2. **Lae-Hoon KIM,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

3. **Hannes PESSENTHEINER,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

4. **Shuhua ZHANG,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

5. **Sanghyun CHI,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

6. **Erik VISSER,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

7. **Shankar THAGADUR SHIVAPPA,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SPATIAL AUDIO WIND NOISE DETECTION** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s)**. **17/128,544** filed **December 21, 2020**, **Qualcomm Reference Number 2101125**, and all provisional applications relating thereto, (and do hereby authorize

ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at SAN DIEGO, CA, USA, on 1/8/2021
City, State, Country Date
S M Akramus SALEHIN

Done at __________, on __________
City, State, Country Date
Lae-Hoon KIM

Done at __________, on __________
City, State, Country Date
Hannes PESSENTHEINER

Done at __________, on __________
City, State, Country Date
Shuhua ZHANG

Done at __________, on __________
City, State, Country Date
Sanghyun CHI

Done at __________, on __________
City, State, Country Date
Erik VISSER

Done at __________, on __________
City, State, Country Date
Shankar THAGADUR SHIVAPPA

ASSIGNMENT

WHEREAS, WE,

1. **S M Akramus SALEHIN,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

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7. **Shankar THAGADUR SHIVAPPA,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

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WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ________________, on ________________ ________________________________
City, State, Country Date **S M Akramus SALEHIN**

Done at San Diego, CA, on 1/20/2021 Laehoon Kim
City, State, Country Date **Lae-Hoon KIM**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Hannes PESSENTHEINER**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Shuhua ZHANG**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Sanghyun CHI**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Erik VISSER**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Shankar THAGADUR SHIVAPPA**

ASSIGNMENT

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7. **Shankar THAGADUR SHIVAPPA**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

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WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **S M Akramus SALEHIN**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Lae-Hoon KIM**

Done at Graz, Styria, AT, on 12/20/2020 ______________________________
City, State, Country Date **Hannes PESSENTHEINER**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Shuhua ZHANG**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Sanghyun CHI**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Erik VISSER**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Shankar THAGADUR SHIVAPPA**

ASSIGNMENT

WHEREAS, WE,

1. **S M Akramus SALEHIN,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

2. **Lae-Hoon KIM,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

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have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SPATIAL AUDIO WIND NOISE DETECTION** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

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AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ________________, on ________________ ________________________________
City, State, Country Date **S M Akramus SALEHIN**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Lae-Hoon KIM**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Hannes PESSENTHEINER**

Done at San Diego, on 1/8/2021 ________________________________
City, State, Country Date **Shuhua ZHANG**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Sanghyun CHI**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Erik VISSER**

Done at ________________, on ________________ ________________________________
City, State, Country Date **Shankar THAGADUR SHIVAPPA**

ASSIGNMENT

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1. **S M Akramus SALEHIN**, having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

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AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **S M Akramus SALEHIN**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Lae-Hoon KIM**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Hannes PESSENTHEINER**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Shuhua ZHANG**

Done at San Diego, on 12/31/2020 ______________________________
City, State, Country Date **Sanghyun CHI**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Erik VISSER**

Done at ____________________, on ____________________ ______________________________
City, State, Country Date **Shankar THAGADUR SHIVAPPA**

ASSIGNMENT

WHEREAS, WE,

1. **S M Akramus SALEHIN,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

2. **Lae-Hoon KIM,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

3. **Hannes PESSENTHEINER,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

4. **Shuhua ZHANG,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

5. **Sanghyun CHI,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

6. **Erik VISSER,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

7. **Shankar THAGADUR SHIVAPPA,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SPATIAL AUDIO WIND NOISE DETECTION** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s)**. **17/128,544** filed **December 21, 2020**, **Qualcomm Reference Number 2101125**, and all provisional applications relating thereto, (and do hereby authorize

ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ______________, on ______________ ______________________
City, State, Country Date **S M Akramus SALEHIN**

Done at ______________, on ______________ ______________________
City, State, Country Date **Lae-Hoon KIM**

Done at ______________, on ______________ ______________________
City, State, Country Date **Hannes PESSENTHEINER**

Done at ______________, on ______________ ______________________
City, State, Country Date **Shuhua ZHANG**

Done at ______________, on ______________ ______________________
City, State, Country Date **Sanghyun CHI**

Done at SAN DIEGO, on 12/31/2020 ______________________
City, State, Country Date **Erik VISSER**

Done at ______________, on ______________ ______________________
City, State, Country Date **Shankar THAGADUR SHIVAPPA**

ASSIGNMENT

WHEREAS, WE,

1. **S M Akramus SALEHIN,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

2. **Lae-Hoon KIM,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

3. **Hannes PESSENTHEINER,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

4. **Shuhua ZHANG,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

5. **Sanghyun CHI,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

6. **Erik VISSER,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

7. **Shankar THAGADUR SHIVAPPA,** having a mailing address located at **5775 Morehouse Drive, San Diego, CA 92121**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **SPATIAL AUDIO WIND NOISE DETECTION** (collectively the "**INVENTIONS**") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "**ASSIGNEE**"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s)**. **17/128,544** filed **December 21, 2020**, **Qualcomm Reference Number 2101125**, and all provisional applications relating thereto, (and do hereby authorize

ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

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AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at ____________________, on ____________________
City, State, Country — Date

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S M Akramus SALEHIN

Done at ____________________, on ____________________
City, State, Country — Date

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Lae-Hoon KIM

Done at ____________________, on ____________________
City, State, Country — Date

____
Hannes PESSENTHEINER

Done at ____________________, on ____________________
City, State, Country — Date

____
Shuhua ZHANG

Done at ____________________, on ____________________
City, State, Country — Date

____
Sanghyun CHI

Done at ____________________, on ____________________
City, State, Country — Date

____
Erik VISSER

Done at San Diego CA USA, on Jan 6th 2021
City, State, Country — Date

____
Shankar THAGADUR SHIVAPPA